	Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ***: Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2016-01-07
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Emilio Castelli	**Representative Title**	APG Material Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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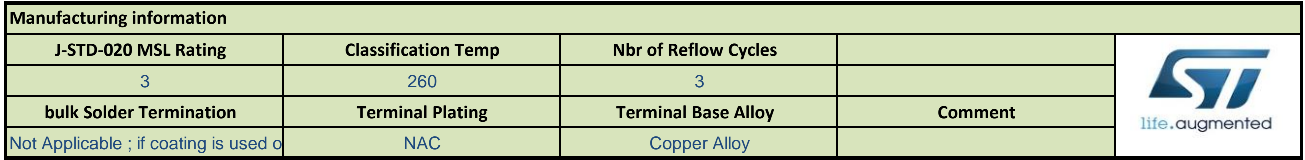
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STA1095EOA	95XO*V860BCQ	A	MU1A	2016-01-07
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	695.0	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used o	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	16x16x1.7	361	flat	

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	**Description**

QueryList : REACH-16th June 2014				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	95XO*V860BCQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies or Wafer	Other inorganic materials	30.877	mg	supplier	die	Silicon (Si)	7440-21-3		28.123	mg	910807	40465
Die or Dies or Wafer				supplier	metallisation	Aluminium (Al)	7429-90-5		0.194	mg	6283	279
Die or Dies or Wafer				supplier	metallisation	Copper (Cu)	7440-50-8		0.576	mg	18655	829
Die or Dies or Wafer				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.103	mg	3336	148
Die or Dies or Wafer				supplier	metallisation	Titanium (Ti)	7440-32-6		0.025	mg	810	36
Die or Dies or Wafer				supplier	metallisation	Tungsten (W)	7440-33-7		0.003	mg	97	4
Die or Dies or Wafer				supplier	metallisation	Nickel (Ni)	7440-02-0		0.002	mg	65	3
Die or Dies or Wafer				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.138	mg	4469	199
Die or Dies or Wafer				supplier	passivation	Silicon Oxide	7631-86-9		0.713	mg	23092	1026
Die or Dies or Wafer				SVHC	passivation	Lead Oxide (PbO)	1317-36-8		1.000	mg	32387	1439
substrate	Other Organic Materials	209.196	mg	supplier	core material	Fiber glass	65997-17-3		64.768	mg	309604	93191
substrate				supplier	core material	Bisphenol F type epoxy resin	9003-36-5		36.064	mg	172393	51891
substrate				supplier	core material	metal hydroxide	21645-51-2		1.472	mg	7036	2118
substrate				supplier	core material	Zinc hydroxyde	20427-58-1		0.294	mg	1405	423
substrate				supplier	core material	Calcium sulfate	7778-18-9		0.736	mg	3518	1059
substrate				supplier	core material	Bismaleimide (B)	105391-33-1		21.933	mg	104844	31558
substrate				supplier	core material	Triazine (T)	25722-66-1		21.933	mg	104844	31558
substrate				supplier	Solder mask	Barium sulfate	7727-43-7		2.814	mg	13452	4049
substrate				supplier	Solder mask	(2-methoxymethylethoxy)propanol	34590-94-8		0.469	mg	2242	675
substrate				supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6		1.563	mg	7471	2249
substrate				supplier	Solder mask	Quartz	14808-60-7		1.563	mg	7471	2249
substrate				supplier	Solder mask	Acrylic resin	9003-01-4		6.471	mg	30933	9311
substrate				supplier	Solder mask	Epoxy resin	29690-82-2		2.126	mg	10163	3059
substrate				#N/A	Solder mask	aromatic hydrocarbon	Proprietary		0.617	mg	2949	888
substrate				supplier	Solder mask	Chlorine	22537-15-1		0.006	mg	29	9
substrate				supplier	Solder mask	Bromine	7726-95-6		0.002	mg	10	3
substrate				supplier	metallisation	Copper (Cu)	7440-50-8		42.672	mg	203981	61399
substrate				supplier	metallisation	Nickel (Ni)	7440-02-0		3.270	mg	15631	4705
substrate				supplier	metallisation	Gold (Au)	7440-57-5		0.423	mg	2022	609
Die attach		7.143	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		6.354	mg	889542	9142
Die attach				supplier	glue or tape	Neopentyl glycol dimethacrylate	1985-51-9		0.357	mg	49979	514
Die attach				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.393	mg	55019	565
Die attach				supplier	glue or tape	palmitic acid	57-10-3		0.007	mg	980	10
Die attach				supplier	glue or tape	4-tert-butylcyclohexanol	98-52-2		0.021	mg	2940	30
Die attach				supplier	glue or tape	Hexamethyltetracosa-hexaene	111-02-4		0.007	mg	980	10
Die attach				supplier	glue or tape	Fluorine trace	14762-94-8		0.004	mg	560	6
Bonding wire		3.416	mg	supplier	wire	Gold (Au)	7440-57-5		3.382	mg	990047	4866
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.034	mg	9953	49
encapsulation		262.910	mg	supplier	mold compound	Silica, vitreous	60676-86-0		203.754	mg	774995	293171
encapsulation				supplier	mold compound	Silica	7631-86-9		26.291	mg	100000	37829
encapsulation				supplier	mold compound	Quartz	14808-60-7		1.315	mg	5002	1892
encapsulation				supplier	mold compound	Epoxy Resin	85954-11-6		15.774	mg	59998	22696
encapsulation				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		3.944	mg	15001	5675
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		10.517	mg	40002	15132
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.315	mg	5002	1892
solder balls	Solder	181.458	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		175.089	mg	964901	251927
solder balls				supplier	solder alloy	Silver (Ag)	7440-22-4		5.444	mg	30001	7833
solder balls				supplier	solder alloy	Copper (Cu)	7440-50-8		0.907	mg	4998	1305
solder balls				JIG - R	solder alloy	Lead (Pb)	7439-92-1		0.018	mg	99	26